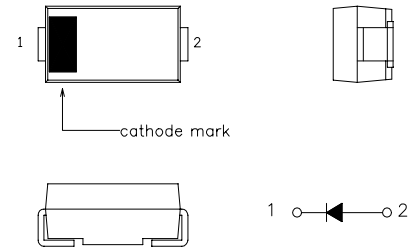


**DIODE**    Type : **EC10DS1**

**FEATURES**

- \* Miniature Size, Surface Mount Device
- \* High Surge Capability
- \* Low Forward Voltage Drop
- \* Low Reverse Leakage Current
- \* Packaged in 12mm Tape and Reel
- \* Not Rolling During Assembly

OUTLINE DRAWING



Maximum Ratings

Approx Net Weight:0.06g

Rating	Symbol	EC10DS1			Unit
Repetitive Peak Reverse Voltage	V <sub>RRM</sub>	100			V
Non-repetitive Peak Reverse Voltage	V <sub>RSM</sub>	250			V
Average Rectified Output Current	I <sub>O</sub>	0.74	Ta=25 °C *1	50Hz Half Sine Wave Resistive Load	A
		1.0	Ta=25 °C *2		
RMS Forward Current	I <sub>F(RMS)</sub>	1.57			A
Surge Forward Current	I <sub>FSM</sub>	25	50Hz Half Sine Wave,1cycle Non-repetitive		A
Operating JunctionTemperature Range	T <sub>jw</sub>	-40 to +150			°C
Storage Temperature Range	T <sub>stg</sub>	-40 to +150			°C

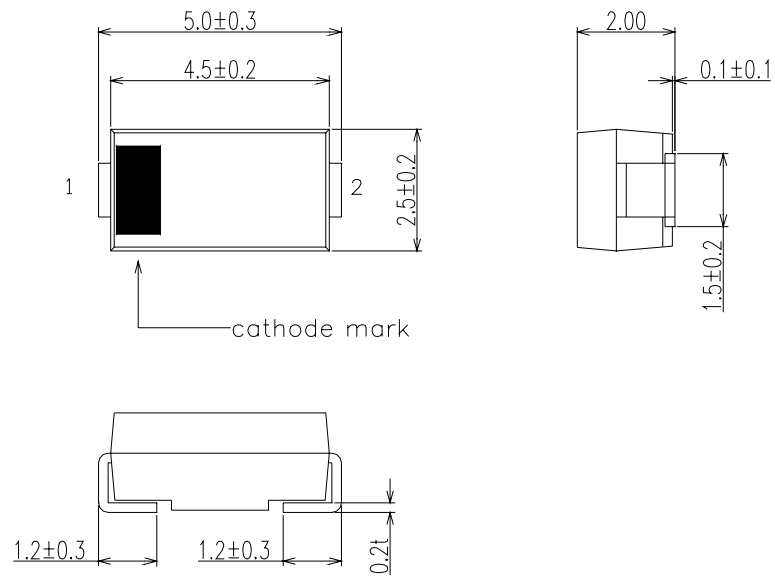
Electrical • Thermal Characteristics

Characteristics	Symbol	Conditions	Min.	Typ.	Max.	Unit
Peak Reverse Current	$I_{RM}$	$T_j=25^{\circ}\text{C}$ , $V_{RM}=V_{RRM}$	-	-	10	$\mu\text{A}$
Peak Forward Voltage	$V_{FM}$	$T_j=25^{\circ}\text{C}$ , $I_{FM}=1.0\text{A}$	-	-	1.1	V
Thermal Resistance	$R_{th(j-a)}$	Junction to Ambient	*1	-	157	$^{\circ}\text{C}/\text{W}$
			*2	-	108	

\*1 Glass Epoxy Substrate Mounted (Soldering Lands=2x2mm, Both Sides)

\*2 Alumina Substrate Mounted (Soldering Lands=2x2mm, Both Sides)

# EC10DS1 OUTLINE DRAWING (Dimensions in mm)



SOLDERING PAD

